BGU7032

1 GHz wideband low-noise amplifier with bypass

Rev. 2 — 14 September 2010 Product data sheet

1. Product profile

1.1 General description

The BGU7032 MMIC is a wideband amplifier with bypass mode. It is designed specifically for high linearity, low-noise applications over a frequency range of 40 MHz to 1 GHz. It is especially suited to Set-Top Box applications.

The LNA is housed in a 6-pin SOT363 plastic SMD package.

CAUTION

This device is sensitive to ElectroStatic Discharge (ESD). Therefore care should be taken during transport and handling.

1.2 Features and benefits

- Internally biased
- Programmable between G_p = 10 dB and bypass
- Flat gain between 40 MHz and 1 GHz
- Noise figure of 4.5 dB
- High linearity with an $IP3_O$ of 29 dBm
- 75 Ω input and output impedance
- Power-down during bypass mode
- Bypass mode current consumption < 5 mA
- ESD protection > 2 kV Human Body Model (HBM) on all pins

1.3 Applications

- Terrestrial and cable Set-Top Boxes (STB)
- Silicon and “Can” tuners
- Personal and Digital Video Recorders (PVR and DVR)
- Home networking and in-house signal distribution

1.4 Quick reference data

Table 1. Quick reference data

T_{amb} = 25 °C; typical values at V_{CC} = 5 V; Z_S = Z_L = 75 Ω; R_{bias} = 43 Ω; 40 MHz ≤ f_1 ≤ 1000 MHz.

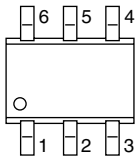
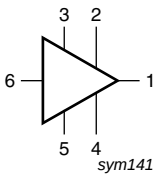
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{CC}	supply voltage	RF input AC coupled		4.75	5.0	5.25	V
$I_{CC(tot)}$	total supply current	G_p = 10 dB mode	[1]	-	43	-	mA
		bypass mode	[1]	-	4	-	mA
T_{amb}	ambient temperature			−10	-	+70	°C
NF	noise figure	G_p = 10 dB mode	[1]	-	4.5	-	dB
		bypass mode	[1]	-	2.5	-	dB
$P_{L(1dB)}$	output power at 1 dB gain compression	1 GHz; G_p = 10 dB mode	[1]	-	14	-	dBm
$IP3_O$	output third-order intercept point	G_p = 10 dB mode	[1][2]	-	29	-	dBm

[1] Mode depends on setting of V_{CTRL}; see Table 8.

[2] The fundamental frequency (f_1) is 1000 MHz. The intermodulation product (IM3) is $2 \times f_2 - f_1$, where $f_2 = f_1 \pm 1$ MHz. Input power P_i = −10 dBm.

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	RF_OUT		
2	V_{CC}		
3	n.c.		
4	CTRL		
5	GND		
6	RF_IN		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BGU7032	-	plastic surface-mounted package; 6 leads	SOT363

4. Marking

Table 4. Marking codes

Type number	Marking code
BGU7032	SD%

Note: % character indicates the location of production.

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5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage	RF input AC coupled		–0.6	5.25	V
$V_{ctrl(Gp)}$	power gain control voltage	pin CTRL	[1]	0	V_{CC}	V
$I_{CC(tot)}$	total supply current			-	60	mA
P_{tot}	total power dissipation	$T_{sp} \leq 100$ °C	[2]	-	250	mW
P_i	input power	single tone		-	10	dBm
T_{stg}	storage temperature			–65	+150	°C
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			–10	+70	°C
V_{ESD}	electrostatic discharge voltage	Human Body Model (HBM); according to JEDEC standard 22-A114E		2	-	kV

[1] $V_{ctrl(Gp)}$ must not exceed V_{CC}; I_{CTRL} must be limited to 5 mA (maximum).

[2] T_{sp} is the temperature at the solder point of the ground lead.

Remark: $V_{ctrl(Gp)}$ must not exceed V_{CC}; I_{CTRL} must be limited to a maximum of 5 mA.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		240	K/W

7. Characteristics

Table 7. Characteristics

T_{amb} = 25 °C; typical values at V_{CC} = 5 V; $Z_S = Z_L$ = 75 Ω; R_{bias} = 43 Ω; 40 MHz ≤ f_1 ≤ 1000 MHz.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{CC}	supply voltage	RF input AC coupled		4.75	5.0	5.25	V
$I_{CC(tot)}$	total supply current	G_p = 10 dB mode	[1]	-	43	-	mA
		bypass mode	[1]	-	4	-	mA
$\|s_{21}\|^2$	insertion power gain	G_p = 10 dB mode	[1]	-	10	-	dB
		bypass mode	[1]	-	–2	-	dB
SL_{sl}	slope straight line			-	–1	-	dB
FL	flatness of frequency response			-	–0.2	-	dB
NF	noise figure	G_p = 10 dB mode	[1]	-	4.5	-	dB
		bypass mode	[1]	-	2.5	-	dB
RL_{in}	input return loss	G_p = 10 dB mode	[1]	-	18	-	dB
		bypass mode	[1]	-	8	-	dB

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Table 7. Characteristics *...continued*

T_{amb} = 25 °C; typical values at V_{CC} = 5 V; Z_S = Z_L = 75 Ω; R_{bias} = 43 Ω; 40 MHz ≤ f_1 ≤ 1000 MHz.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
RL_{out}	output return loss	G_p = 10 dB mode	[1]	-	12	-	dB
		bypass mode	[1]	-	8	-	dB
$P_{L(1dB)}$	output power at 1 dB gain compression	1 GHz; G_p = 10 dB mode	[1]	-	14	-	dBm
$IP3_O$	output third-order intercept point	G_p = 10 dB mode	[1][2]	-	29	-	dBm
		bypass mode	[1][2]	-	29	-	dBm

[1] Mode depends on setting of $V_{ctrl(Gp)}$ (V_{CTRL}); see Table 8.

[2] The fundamental frequency (f_1) is 1000 MHz. The intermodulation product (IM3) is $2 \times f_2 - f_1$, where $f_2 = f_1 \pm 1$ MHz. Input power P_i = –10 dBm.

Table 8. Gain selection (pin CTRL)

–10 °C ≤ T_{amb} ≤ +70 °C; recommended power-up condition: V_{CTRL} = logic 0 or < 0.7 V.

$V_{ctrl(Gp)}$ (V_{CTRL}) (V)	Mode
≤ 0.7	bypass
≥ 4.3	G_p = 10 dB

Remark: $V_{ctrl(Gp)}$ must not exceed V_{CC}; I_{CTRL} must be limited to a maximum of 5 mA.

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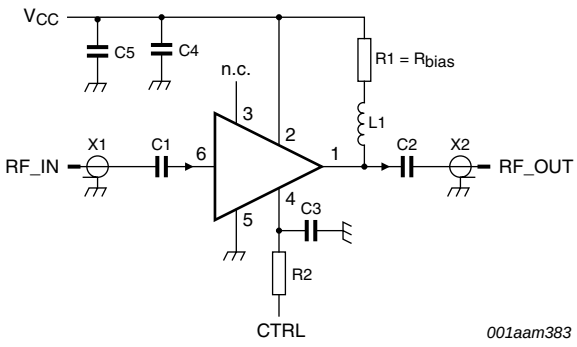
8. Application information

Other applications are possible. Please contact your local sales representative for more information. Application notes are available on the NXP website.

8.1 Application circuit

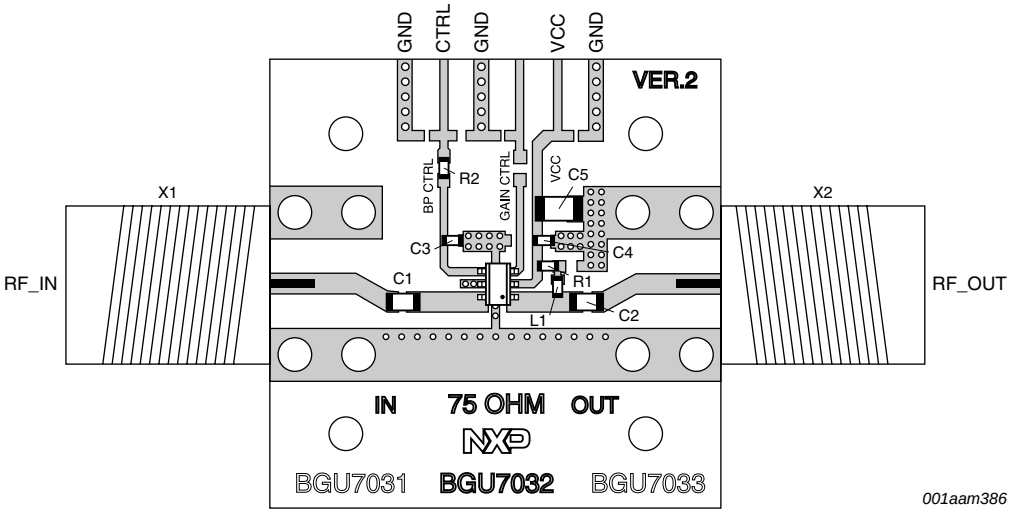


Components are listed in Table 9.

Fig 1. BGU7032 application circuit

All control and supply lines must be decoupled properly. The decoupling capacitors must be placed as close to the device as possible.

8.2 Application circuit board layout



PCB material = FR4.

PCB thickness = 1.6 mm.

PCB size = 30 mm × 30 mm.

ε_r = 4.5; thickness of copper layer = 35 μm.

Components are listed in Table 9.

Fig 2. BGU7032 application circuit board layout

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Table 9. List of components

See Figure 1 and Figure 2.

Component	Description	Value		Remarks	Function
C1, C2	capacitor	10 nF			DC blocking
C3, C4	capacitor	10 nF			decoupling
C5	capacitor	10 μF			decoupling
L1	chip ferrite bead	1.5 kΩ	[1]	Murata BLM18HE152SN1DF	RF choke
R1	resistor	43 Ω	[1]	R_{bias}	bias setting
R2	resistor	1.8 kΩ			current limiting
X1, X2	connector	75 Ω		F-connector, edge mount PCB reflow type, Bomar 861V509ERG	input/output

[1] L1 and R1 must have a power rating of 0.1 W or higher.

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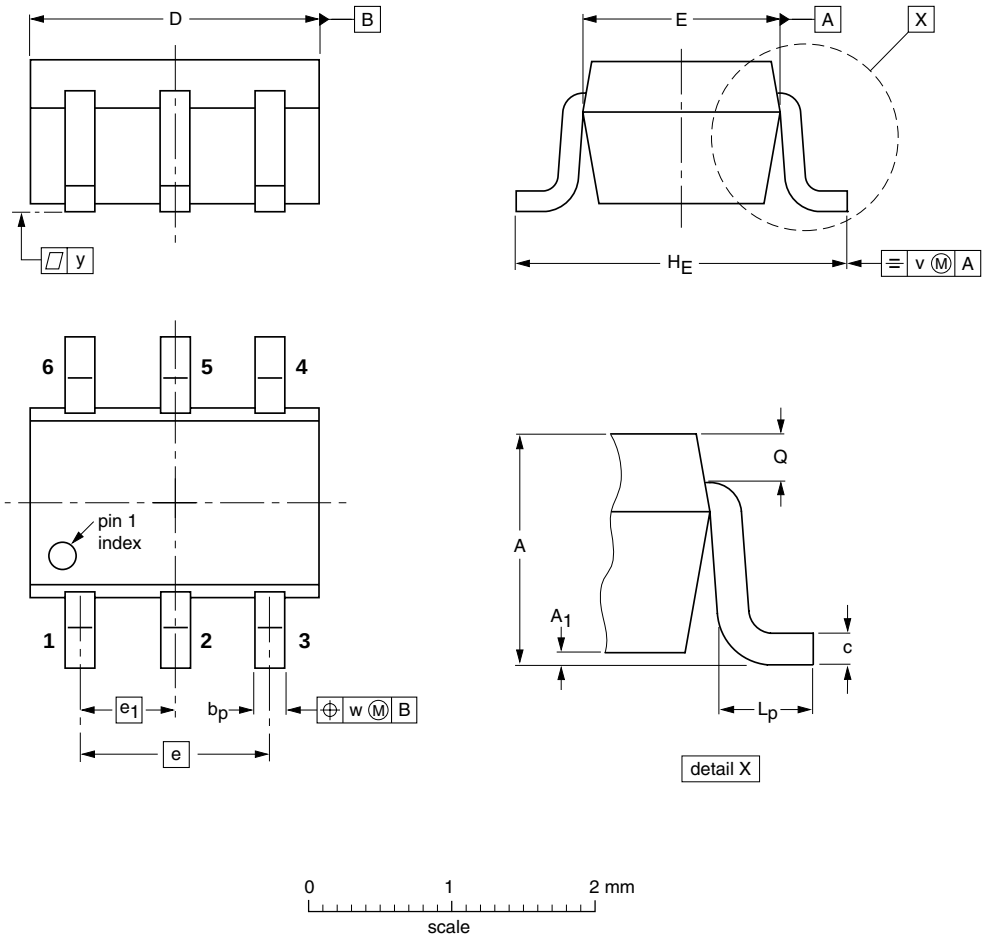
9. Package outline

Plastic surface-mounted package; 6 leads **SOT363**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w	y
mm	1.1 0.8	0.1	0.30 0.20	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.25 0.15	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT363			SC-88			~~04-11-08~~ 06-03-16

Fig 3. Package outline SOT363

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10. Abbreviations

Table 10. Abbreviations

Acronym	Description
AC	Alternating Current
DC	Direct Current
LNA	Low-Noise Amplifier
MMIC	Monolithic Microwave Integrated Circuit
PCB	Printed-Circuit Board
RF	Radio Frequency
SMD	Surface-Mounted Device

11. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BGU7032 v.2	20100914	Product data sheet	-	BGU7032 v.1
Modifications:	• The status of this data sheet has been changed to Product data sheet.			
BGU7032 v.1	20100817	Preliminary data sheet	-	-

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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